

REVISION RECORD			
REV	ECD	DESCRIPTION	DRFT

NOTES:

MATERIAL:

1. HOUSING MATERIAL :GLASS FILLED POLYESTER UL94V-0.
 2. CONTACT MATERIAL :PHOSPHOR BRONZE t=0.30mm.
 3. PLATING :SELECTING GOLD PLATING 3u~50u"0 NICKEL IN CONTACT AREA. 150u" TIN PLATING OVER NICKEL IN SOLDER ARE
 4. SHIELD: :0.20mmTHICKNESS COPPER ALLY WITH NICKEL PL
- ELECTRICAL:

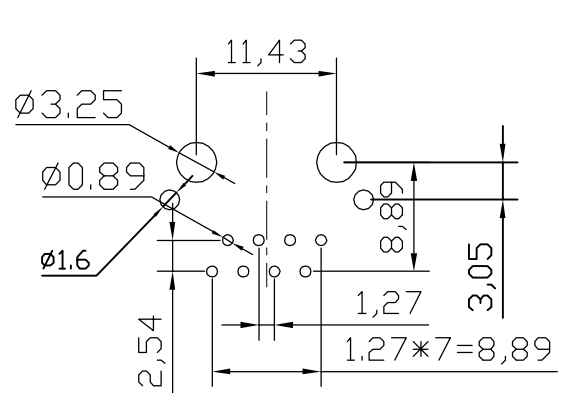
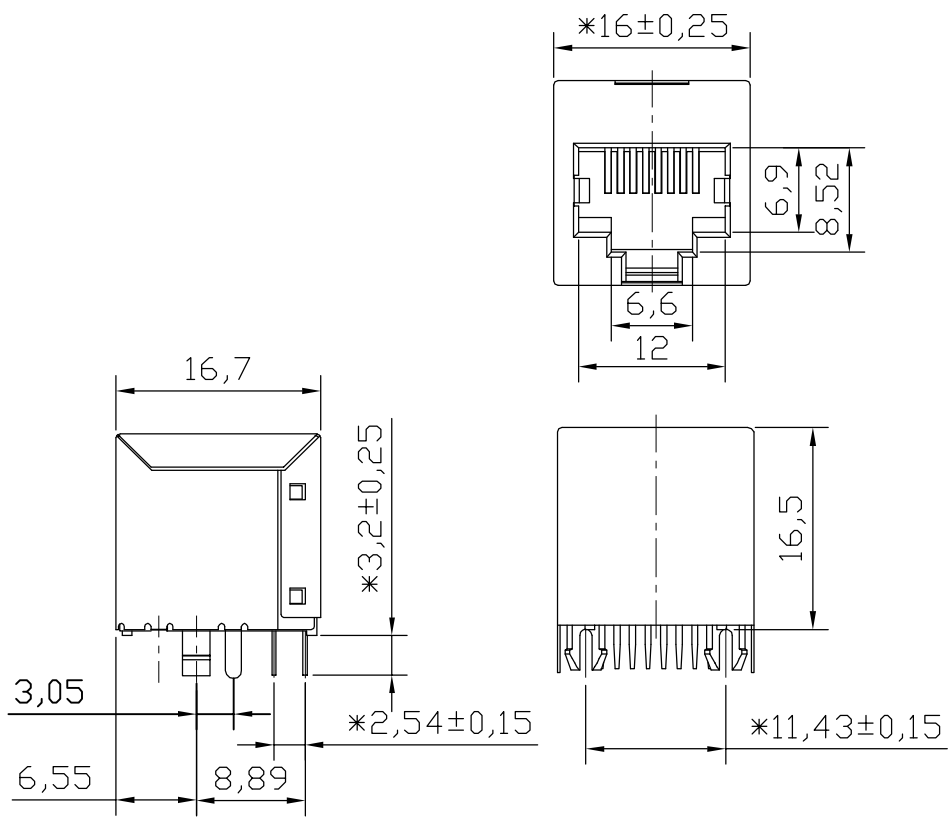
1. VOLTAGE RATING :125 VAC RMS.
2. CURRENT RATING :1.5 AMP.
3. CONTACT RESISTANCE :30 MILLIOHMS MAX.
4. INSULATION RESISTANCE :500 MEGOHMS MIN @ 500V DC .
5. DIELECTRIC WITHSTANDING RESISTANCE

MECHANICAL:

1. DURRABILITY: :750 CYCLES MIN.
2. PCB RETENTION PRE-SOLDER :1 LB MIN.

ENVIRONMENTAL:

1. STORAGE : -40° C TO 85° C.
2. OPERATION : 0° C TO 70° C.



PC Board Layout
Component Side Shown

MM (INCH)		DFTO: SHB	DATE: 2007.05.05	Coorle Technology	
TOLERANCES EXCEPT AS NOTED		CHKD: LANBD	DATE: 2007.05.05		
MM		MFO:	DATE:	DRAWING NO. TE52E1002	SIZE A3
.0 ± 0.15	±	APPVL:	DATE:	/PART NO.	
.00 ± 0.075	±	MATERIAL :		DRAWING NOT SCALE DRAWING	
.000 ± 0.05	±	QTY :		SHEET	
ANGLES ± 0.5		FINISH :		□	
THIRD ANGLE PROJECTION		SCALE :		□	